

APB3025YSGC YELLOW/SUPER BRIGHT GREEN

Features

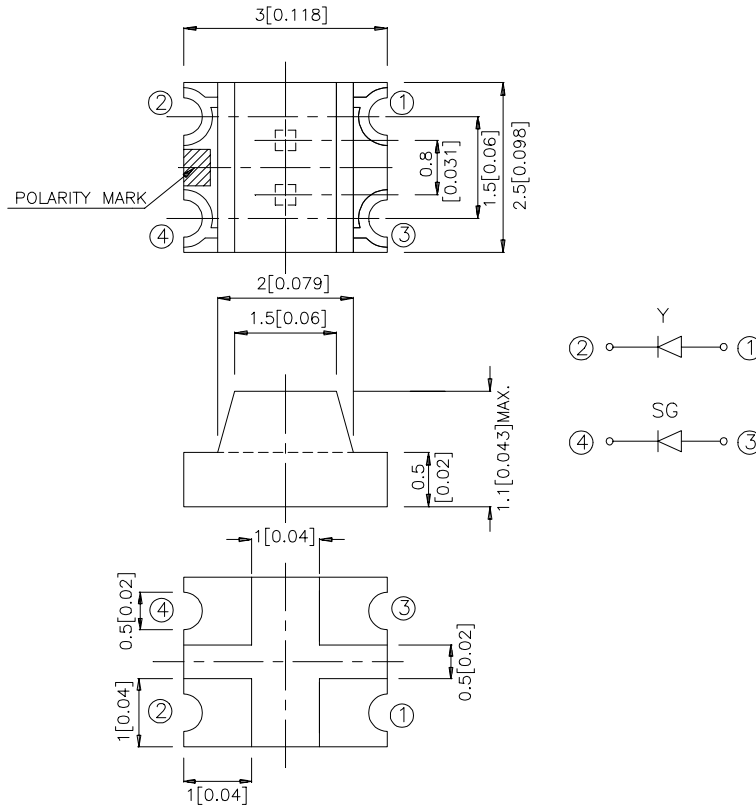
- 3.0mmx2.5mm SMT LED, 1.1mm THICKNESS.
- BI-COLOR, LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.

Description

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2(0.0079)$ unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	2θ1/2
APB3025YSGC	YELLOW (GaAsP/GaP)	WATER CLEAR	2.6	8	120°
	SUPER BRIGHT GREEN (GaP)		2.6	12	

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at T_A=25°C

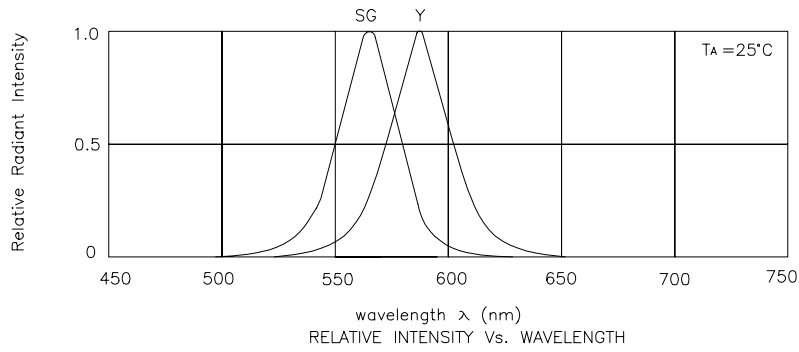
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Yellow Super Bright Green	590 565		nm	I _F =20mA
λ _D	Dominate Wavelength	Yellow Super Bright Green	588 568		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	Yellow Super Bright Green	35 30		nm	I _F =20mA
C	Capacitance	Yellow Super Bright Green	20 15		pF	V _F =0V;f=1MHz
V _F	Forward Voltage	Yellow Super Bright Green	2.1 2.2	2.5 2.5	V	I _F =20mA
I _R	Reverse Current	All		10	uA	V _R = 5V

Absolute Maximum Ratings at T_A=25°C

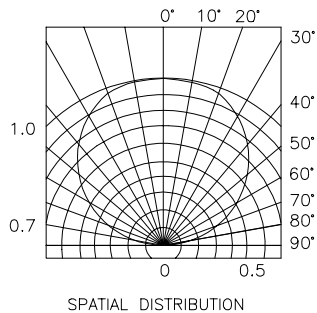
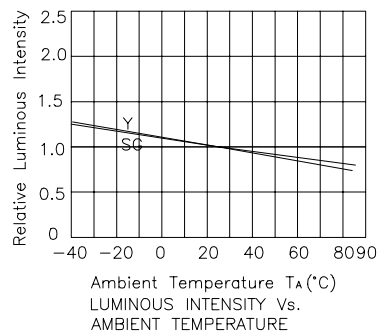
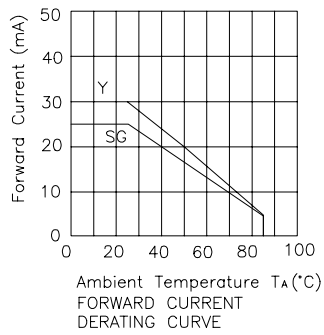
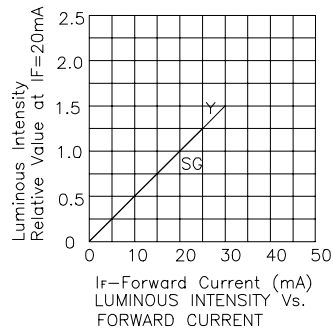
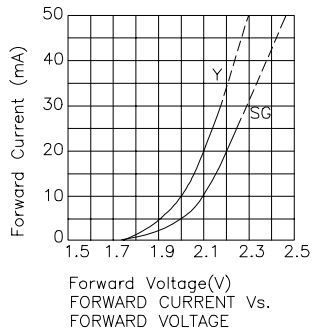
Parameter	Yellow	Super Bright Green	Units
Power dissipation	105	105	mW
DC Forward Current	30	25	mA
Peak Forward Current [1]	140	140	mA
Reverse Voltage	5		V
Operating/Storage Temperature	-40°C To +85°C		

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

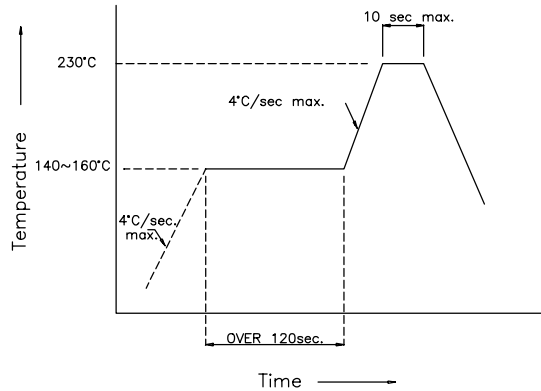


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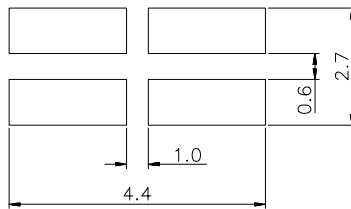


APB3025YSGC SMT Reflow Soldering Instruction

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

